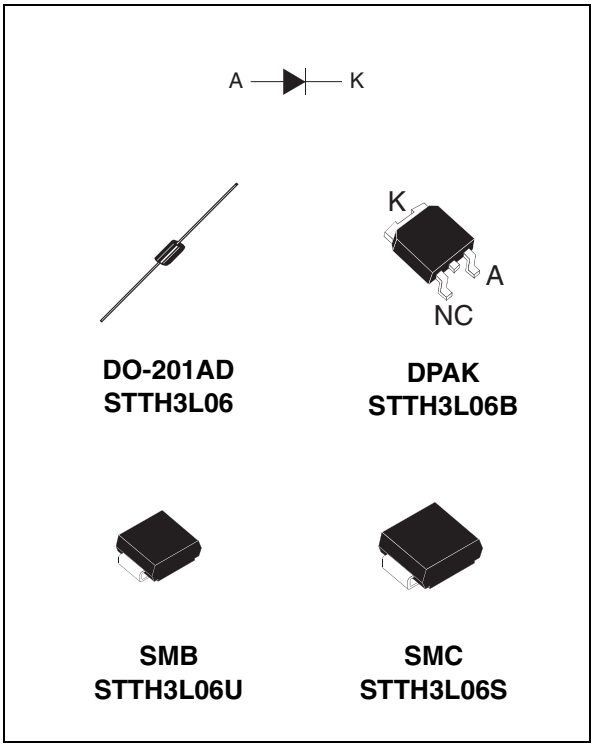
STTH3L06

TURBO 2 ULTRAFAST HIGH VOLTAGE RECTIFIER

Table 1: Main Product Characteristics

$I_{F(AV)}$	3 A
V_{RRM}	600 V
I_R (max)	100 µA
T_j	175°C
V_F (typ)	0.85 V
t_{rr} (typ)	60 ns



DO-201AD
STTH3L06

DPAK
STTH3L06B

SMB
STTH3L06U

SMC
STTH3L06S

FEATURES AND BENEFITS

- Ultrafast switching
- Low forward voltage drop
- Low thermal resistance
- Low leakage current (platinium doping)

DESCRIPTION

The STTH3L06, which is using ST Turbo 2 600V technology, is specially suited as boost diode in discontinuous or critical mode power factor corrections.
This device is intended for use as a free wheeling diode in power supplies and other power switching applications.

Table 2: Order Codes

Part Number	Marking
STTH3L06	STTH3L06
STTH3L06RL	STTH3L06
STTH3L06B	STTH3L06B
STTH3L06B-TR	STTH3L06B
STTH3L06U	3L06U
STTH3L06S	S06

Table 3: Absolute Ratings (limiting values)

Symbol	Parameter			Value	Unit
V_{RRM}	Repetitive peak reverse voltage			600	V
$I_{F(RMS)}$	RMS forward voltage	DO-201AD / SMB / SMC		10	A
		DPAK		6	
$I_{F(AV)}$	Average forward current $\delta = 0.5$	DO-201AD	Tl = 100°C	3	A
		DPAK	Tl = 155°C		
		SMB	Tl = 80°C		
		SMC	Tl = 100°C		
I_{FSM}	Surge non repetitive forward current	DO-201AD	tp = 10ms sinusoidal	70	A
		SMB / SMC		60	
		DPAK		40	
T_{stg}	Storage temperature range			-65 to + 175	°C
T_j	Maximum operating junction temperature			175	°C

Table 4: Thermal Parameters

Symbol	Parameter		Maximum	Unit
$R_{th(j-l)}$	Junction to lead	DO-201AD L = 10 mm	20	°C/W
		DPAK	5.5	
		SMB	25	
		SMC	20	
$R_{th(j-a)}$	Junction to ambient (see fig. 13)	DO-201AD L = 10 mm	75	°C/W

Table 5: Static Electrical Characteristics

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
I_R	Reverse leakage current	T_j = 25°C	$V_R = V_{RRM}$			3	µA
		T_j = 150°C			15	100	
V_F	Forward voltage drop	T_j = 25°C	I_F = 3A			1.3	V
		T_j = 150°C			0.85	1.05	

To evaluate the conduction losses use the following equation: $P = 0.89 \times I_{F(AV)} + 0.055\ I_F{}^2{}_{(RMS)}$

Table 6: Dynamic Characteristics

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
t_{rr}	Reverse recovery time	T_j = 25°C	I_F = 1A dI_F/dt = -50 A/µs V_R =30V		60	85	ns
t_{fr}	Forward recovery time	T_j = 25°C	I_F = 3A dI_F/dt = 100 A/µs $V_{FR} = 1.1 \times V_{Fmax}$			100	ns
V_{FP}	Forward recovery voltage		I_F = 3A dI_F/dt = 100 A/µs			7.5	V

Figure 1: Conduction losses versus average current

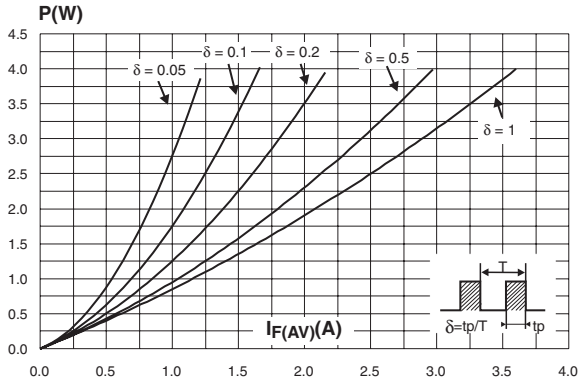


Figure 2: Forward voltage drop versus forward current

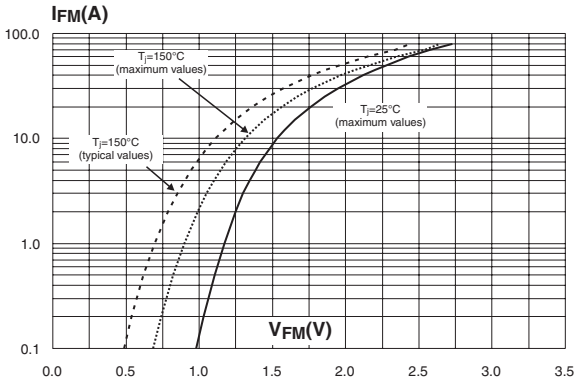


Figure 3: Relative variation of thermal impedance junction ambient versus pulse duration (epoxy printed circuit FR4, L_{leads} = 10mm, S_{CU}=1cm²)

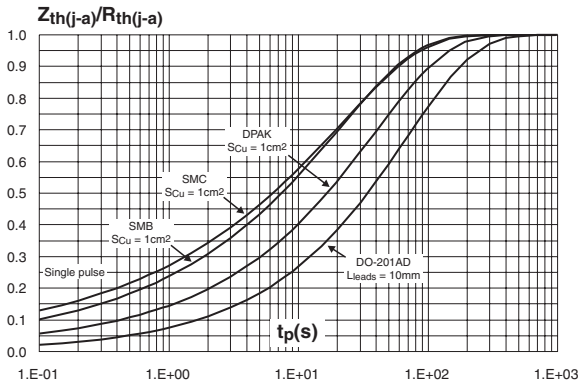


Figure 4: Peak reverse recovery current versus dI_F/dt (typical values)

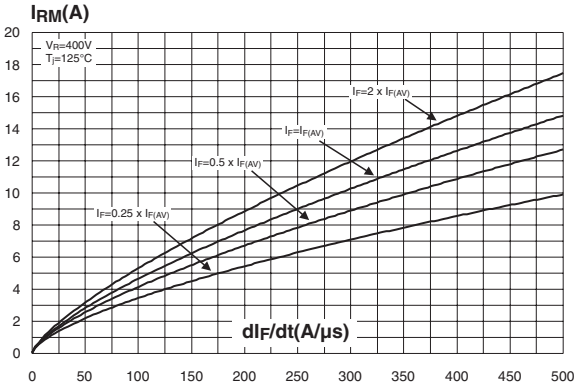


Figure 5: Reverse recovery time versus dI_F/dt (typical values)

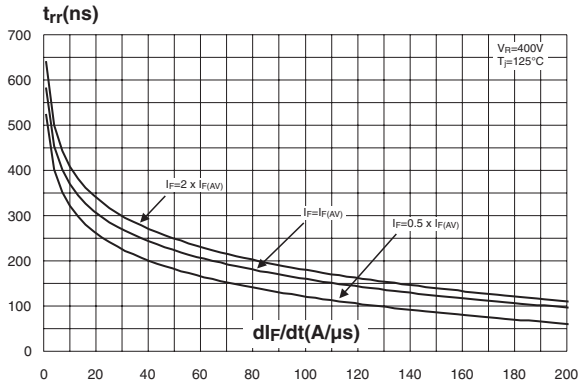


Figure 6: Reverse recovery charges versus dI_F/dt (typical values)

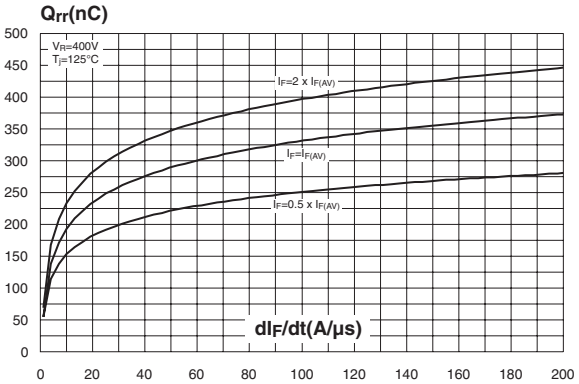


Figure 7: Softness factor versus d_{IF}/dt (typical values)

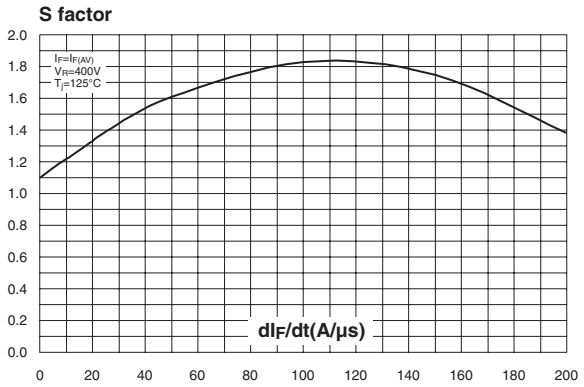


Figure 8: Relative variations of dynamic parameters versus junction temperature

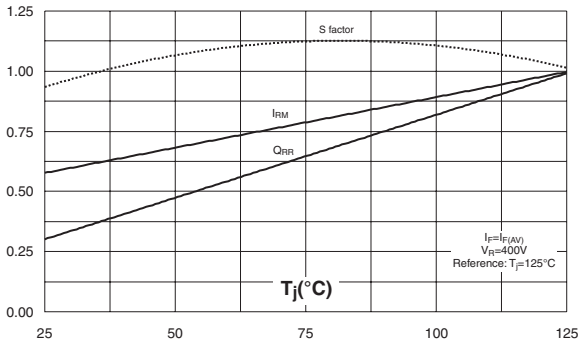


Figure 9: Transient peak forward voltage versus dI_F/dt (typical values)

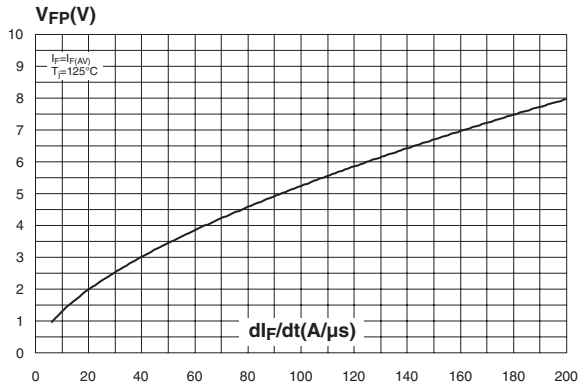


Figure 10: Forward recovery time versus dI_F/dt (typical values)

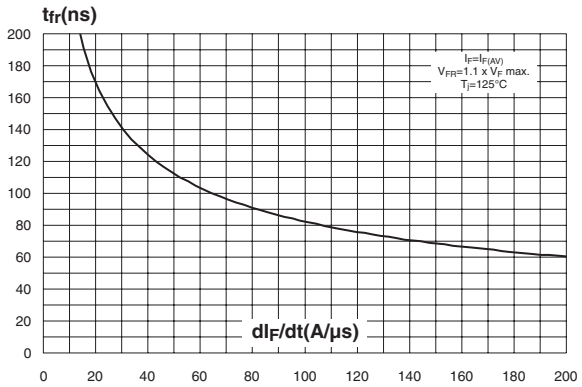


Figure 11: Junction capacitance versus reverse voltage applied (typical values)

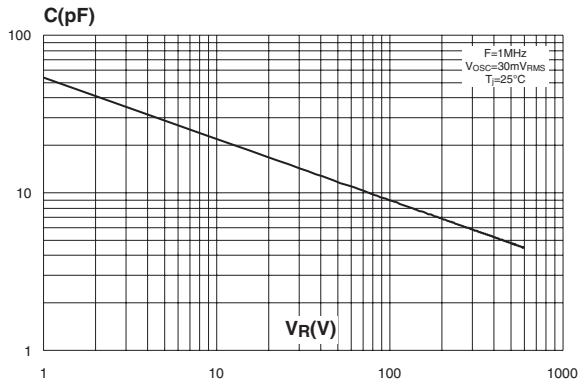


Figure 12: Thermal resistance junction to ambient versus copper surface under lead (epoxy FR4, e_{CU}=35µm) (DO-201AD)

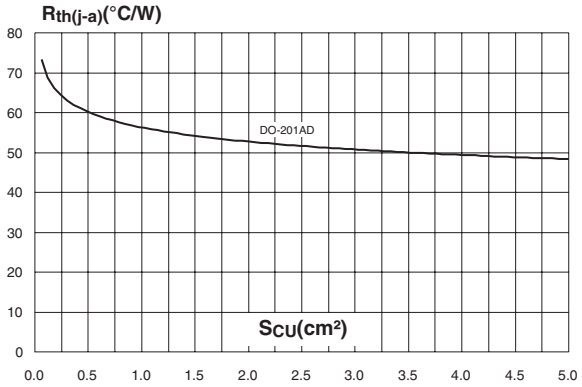


Figure 13: Thermal resistance junction to ambient versus copper surface under lead (epoxy FR4, e_{CU}=35µm) (SMB / SMC)

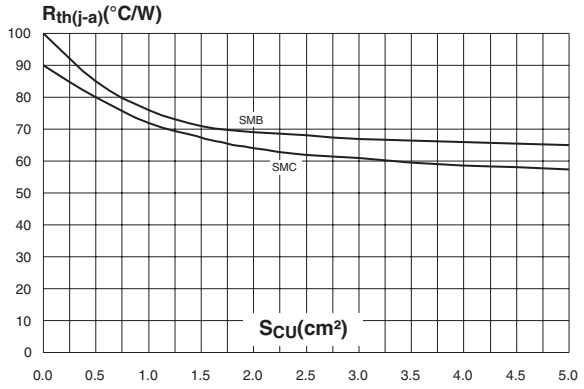


Figure 14: Thermal resistance junction to ambient versus copper surface under tab (epoxy FR4, e_{CU}=35µm) (DPAK)

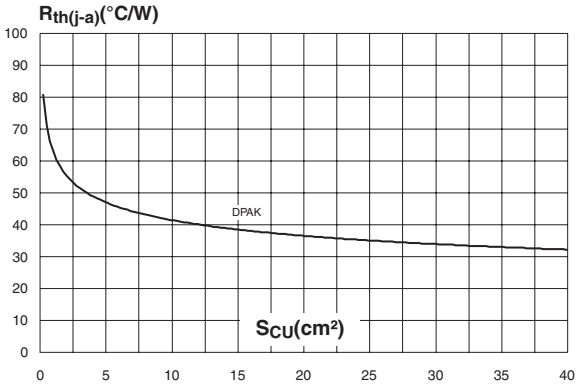


Figure 15: Thermal resistance versus lead length

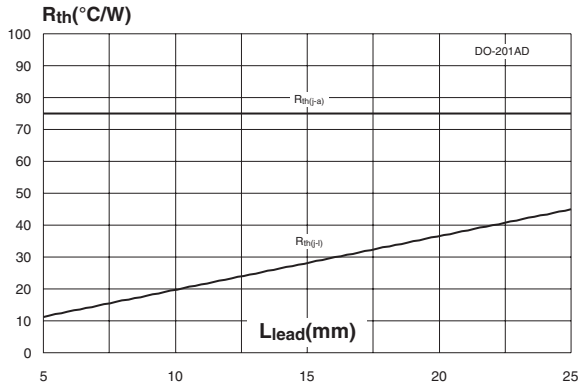
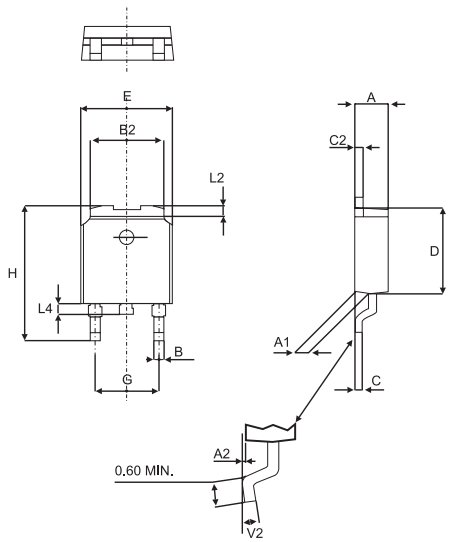


Figure 16: DPAK Package Mechanical Data



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max	Min.	Max.
A	2.20	2.40	0.086	0.094
A1	0.90	1.10	0.035	0.043
A2	0.03	0.23	0.001	0.009
B	0.64	0.90	0.025	0.035
B2	5.20	5.40	0.204	0.212
C	0.45	0.60	0.017	0.023
C2	0.48	0.60	0.018	0.023
D	6.00	6.20	0.236	0.244
E	6.40	6.60	0.251	0.259
G	4.40	4.60	0.173	0.181
H	9.35	10.10	0.368	0.397
L2	0.80 typ.		0.031 typ.	
L4	0.60	1.00	0.023	0.039
V2	0°	8°	0°	8°

Figure 17: DPAK Foot Print Dimensions
(in millimeters)

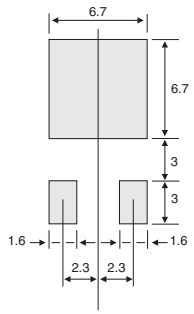
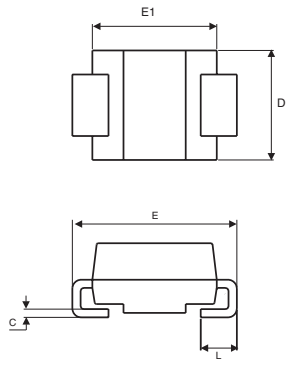


Figure 18: SMB Package Mechanical Data



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	1.95	2.20	0.077	0.087
c	0.15	0.41	0.006	0.016
E	5.10	5.60	0.201	0.220
E1	4.05	4.60	0.159	0.181
D	3.30	3.95	0.130	0.156
L	0.75	1.60	0.030	0.063

Figure 19: SMB Foot Print Dimensions
(in millimeters)

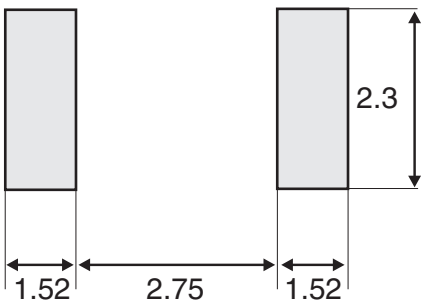
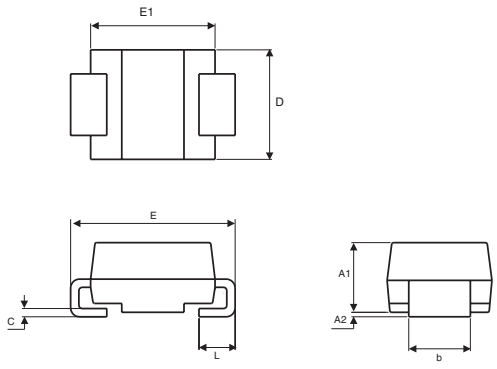


Figure 20: SMC Package Mechanical Data



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.075	0.096
A2	0.05	0.20	0.002	0.008
b	2.90	3.2	0.114	0.126
c	0.15	0.41	0.006	0.016
E	7.75	8.15	0.305	0.321
E1	6.60	7.15	0.260	0.281
E2	4.40	4.70	0.173	0.185
D	5.55	6.25	0.218	0.246
L	0.75	1.60	0.030	0.063

Figure 21: SMC Foot Print Dimensions
(in millimeters)

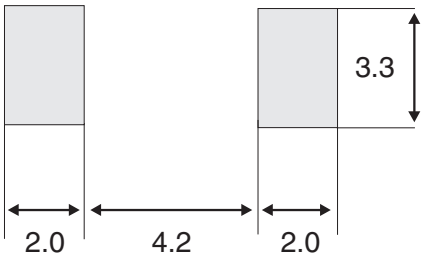
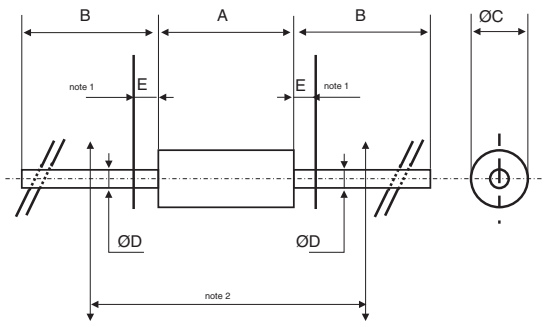


Figure 22: DO-201AD Package Mechanical Data



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A		9.50		0.374
B	25.40		1.000	
C		5.30		0.209
D		1.30		0.051
E		1.25		0.049
NOTES	1 - The lead diameter ø D is not controlled over zone E 2 - The minimum axial length within which the device may be placed with its leads bent at right angles is 0.59"(15 mm)			

Table 7: Ordering Information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STTH3L06	STTH3L06	DO-201AD	1.12 g	600	Ammopack
STTH3L06-RL	STTH3L06	DO-201AD	1.12 g	1900	Tape & reel
STTH3L06B	STTH3L06B	DPAK	0.3 g	75	Tubel
STTH3L06B-TR	STTH3L06B	DPAK	0.3 g	2500	Tape & reel
STTH3L06U	3L06U	SMB	0.11 g	2500	Tape & reel
STTH3L06S	S06	SMC	0.243 g	2500	Tape & reel

- Epoxy meets UL94, V0
- Band indicated cathode (DO-201AD)
- Bending method: see application note **AN1471** (DO-201AD)

Table 8: Revision History

Date	Revision	Description of Changes
October-2001	1	First issue
07-Sep-2004	2	SMB, SMC and DPAK packages added